

# Material Composition Data



Product: CM7V-T1A

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CM7V-T1A -					Sub-Assembly
Sub-Assembly	Material	Substance	CAS No	Mass (mg)	% by mass
<b>Electrodes</b>	Chromium	Cr	7440-47-3	0.001	10.00
	Gold	Au	7440-57-5	0.009	90.00
<b>Epoxy attach</b>	Silver filled Epoxy	Ag	7440-22-4	0.072	80.00
	Silver filled Epoxy	Silicones/siloxanes	68037-58-1	0.009	10.00
	Silver filled Epoxy	Petroleum spirits	64475-85-0	0.009	10.00
<b>Housing</b>	Ceramic	Al <sub>2</sub> O <sub>3</sub>	1344-28-1	6.300	100.00
<b>Metal lid</b>	0.1 micron gold over nickel	Au	7440-57-5	0.028	1.00
	0.1 micron gold over nickel	Ni	7440-02-0	0.252	9.00
	0.1 micron gold over nickel	Fe	7439-89-6	1.336	47.70
	0.1 micron gold over nickel	Ni	7440-02-0	0.731	26.10
	0.1 micron gold over nickel	Co	7440-48-4	0.454	16.21
<b>Resonator</b>	Quartz	SiO <sub>2</sub>	14808-60-7	0.130	100.00
<b>Seal</b>	Preform	Au	7440-57-5	0.304	80.00
	Preform	Sn	7440-31-5	0.076	20.00
<b>Terminations</b>	Gold	Au	7440-57-5	0.030	5.08
	Nickel	Ni	7440-02-0	0.089	15.06
	Tungsten	W	7440-33-7	0.472	79.86
<b>Total Mass:</b>				<b>10.302 mg</b>	

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